# GP2L24J0000F

# **Detecting Distance : 0.7mm Darlington Phototransistor Output Compact Reflective Photointerrupter**



## Description

GP2L24J0000F is a compact-package, darlington phototransistor output, reflective photointerrupter, with emitter and detector facing the same direction in a molding that provides non-contact sensing. The compact package series is a result of unique technology, combing transfer and injection molding, that also blocks visible light to minimize false detection.

#### Features

- 1. Reflective with Darlington Phototransistor Output
- 2. Highlights :
  - Compact Size
- 3. Key Parameters :
  - Optimal Sensing Distance : 0.7mm
  - Package : 4×3×1.7mm
  - · Visible light cut resin to prevent
- 4. Lead free and RoHS directive compliant

# Agency approvals/Compliance

1. Compliant with RoHS directive

#### Applications

- 1. Detection of object presence or motion.
- 2. Example : printer, optical storage

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#### Internal Connection Diagram



(Unit : mm)

■ Outline Dimensions



Plating material : SnCu (Cu : TYP. 2%)

# SHARP

# Date code (Symbol)

#### January









September

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July

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March

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April	



October







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#### December



# Rank mark

There is no rank indicator.

# Country of origin Japan

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# IARP

■ Abs	Absolute Maximum Ratings (T <sub>a</sub> =25°C			(T <sub>a</sub> =25°C)
	Parameter	Symbol	Rating	Unit
	Forward current	IF	50	mA
Input	Reverse voltage	V <sub>R</sub>	6	V
	Power dissipation	PD	75	mW
	Collector-emitter voltage	V <sub>CEO</sub>	35	V
Output	Emitter-collector voltage	VECO	6	V
Output	Collector current	I <sub>C</sub>	50	mA
	Collector power dissipation	Pc	75	mW
Total power dissipation		P <sub>tot</sub>	100	mW
Operating temperature		T <sub>opr</sub>	-25 to +85	°C
Storage temperature		T <sub>stg</sub>	-40 to +100	°C
*1Soldering temperature		T <sub>sol</sub>	260	°C



\*1 For 5s or less.

# Electro-optical Characteristics

(T<sub>a</sub>=25°C) Parameter Symbol Condition MIN. TYP. MAX. Unit Forward voltage  $V_{\rm F}$ I<sub>F</sub>=20mA 1.2 1.4 V \_ Input Reverse current  $V_R=6V$ 10 μΑ  $I_R$ \_ \_ Output Collector dark current V<sub>CE</sub>=10V 1 nA  $I_{\text{CEO}}$ \_ \_ \*<sup>2</sup> Collector current  $I_F=4mA, V_{CE}=2V$ 15 0.5 3  $I_{C}$ mA Transfer \*3 Leak current  $I_F=4mA, V_{CE}=5V$ 5  $I_{\text{LEAK}}$ nA \_ \_ charac- $V_{CE}=2V, I_{C}=10\mu A,$ 80 400 Rise time \_  $t_r$ teristics Response time μs Fall time  $R_L=100\Omega$ , d=1mm 70 400  $t_{\mathrm{f}}$ \_

\*2 The condition and arrangement of the reflective object are shown below.

The rank splitting of collector current (I<sub>C</sub>) shall be executed according to the table below.

Rank	$\begin{array}{c} \text{Collector current, } I_C \text{ [mA]} \\ (I_F = 4 \text{mA, } V_{CE} = 2 \text{V}) \end{array}$	Package sleeve color
А	0.5 to 1.9	Yellow
В	1.45 to 5.4	Transparent
С	4 to 15	Green

\*3 Without reflective object.

# Test Arrangement for Collector Current





# Model Line-up

Rank	Collector current I <sub>C</sub> [mA]	
	$(I_F=4mA, V_{CE}=2V, T_a=25^{\circ}C)$	
A, B or C	0.5 to 15	
В	1.45 to 5.4	
С	4 to 15	
A or B	0.5 to 5.4	
B or C	1.45 to 15	
	A, B or C B C A or B	

\* The ratio of each rank can not be guaranteed.

Please contact a local SHARP sales representative to inquire about production status.







# Fig.3 Peak Forward Current vs. Duty Ratio







Fig.2 Collector Power Dissipation vs. Ambient Temperature



# Fig.4 Forward Current vs. Forward Voltage



# Fig.6 Collector Current vs. Collector-emitter Voltage





# Fig.7 Relative Collector Current vs. Ambient Temperature



# Fig.9 Response Time vs. Load Resistance







Fig.8 Collector Dark Current vs. Ambient Temperature



# Fig.10 Test Circuit for Response Time



# Fig.12 Detecting Position Characteristics (1)



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# Fig.13 Detecting Position Characteristics (2)



## Fig.15 Frequency Response



# Fig.14 Test Condition for Distance & Detecting Position Characteristics



# Fig.16 Spectral Sensitivity (Detecting side)



Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.



## Design Considerations

#### Design guide

1) Prevention of detection error

To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

2) Distance characteristic

Please refer to Fig.11 (Relative collector current vs. Distance) to set the distance of the photointerrupter and the object.

This product is not designed against irradiation and incorporates non-coherent IRED.

#### Degradation

In general, the emission of the IRED used in photointerrupter will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

#### Parts

This product is assembled using the below parts.

Photodetector (qty. : 1)

Category	Material	Maximum Sensitivity wavelength (nm)	Sensitivity wavelength (nm)	Response time (µs)
Phototransister	Silicon (Si)	800	700 to 1 200	80

#### • Photo emitter (qty. : 1)

Category	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared emitting diode (non-coherent)	Gallium arsenide (GaAs)	950	0.3

#### Material

Case	Lead frame	Lead frame plating
Black polyphenylene	42Alloy	SnCu plating



#### Manufacturing Guidelines

#### Soldering Method

Flow Soldering:

Soldering should be completed below 260°C and within 5 s.

Soldering area is 1mm or more away from the bottom of housing.

Please take care not to let any external force exert on lead pins.

Please don't do soldering with preheating, and please don't do soldering by reflow.

#### Other notice

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the cooling and soldering conditions.

#### • Cleaning instructions

Solvent cleaning :

Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.

Ultrasonic cleaning :

Do not execute ultrasonic cleaning.

#### Recommended solvent materials :

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

#### • Presence of ODC

This product shall not contain the following materials. And they are not used in the production process for this product. Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).
Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).



## Package specification

# Sleeve package

Package materials Sleeve : Polystyrene Stopper : Styrene-Butadiene

Package method

MAX. 50 pcs. of products shall be packaged in a sleeve. Both ends shall be closed by tabbed and tabless stoppers.

MAX. 40 sleeves in one case.

#### Color of sleeve

Rank classification is distinguished by the color of the sleeve as shown in the table below. But the ratio of each rank can not be guaranteed.

Rank	Color of sleeve	
Α	Yellow	
В	Transparent	
С	Green	

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